NTQD6866

Product Preview

Power MOSFET 5.8 Amps, 20 Volts N-Channel TSSOP-8

Features

- New Low Profile TSSOP-8 Package
- Ultra Low RDS(on)
- Higher Efficiency Extending Battery Life
- Logic Level Gate Drive
- Diode Exhibits High Speed, Soft Recovery
- Avalanche Energy Specified
- I_{DSS} and $V_{DS(on)}$ Specified at Elevated Temperatures

Applications

- Power Management in Portable and Battery–Powered Products, i.e.: Computers, Printers, PCMCIA Cards, Cellular and Cordless Telephones
- Lithium Ion Battery Applications
- Note Book PC

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

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Rating	Symbol	Value	Unit
Drain-to-Source Voltage	VDSS	20	Vdc
Gate-to-Source Voltage - Continuous	VGS	±12	Vdc
Drain Current – Continuous – Continuous @ 70°C – Single Pulse (tp \leq 10 μ s)	I _D ID IDM	5.8 TBD 20	Adc
Total Power Dissipation	PD	1.6	W
Operating and Storage Temperature Range	Тј, T _{stg}	–55 to +150	°C
Single Pulse Drain–to–Source Avalanche Energy – Starting $T_J = 25^{\circ}C$ ($V_{DD} = 20 Vdc, V_{GS} = 5 Vdc,$ $I_L = 10 Apk, L = 10 mH, R_G = 25 \Omega$)	E _{AS}	580	mJ
Thermal Resistance – Junction–to–Ambient (Note 1.) Single Channel Steady State Both Channels Junction–to–Ambient (Note 2.) Both Channels	R _{θJA}	180 176 100	°C/W
Thermal Resistance – Junction–to–Lead Single Channel Both Channels Steady State	R _{θJL}	27 24	°C/W

1. Surface Mounted to Min Pad.

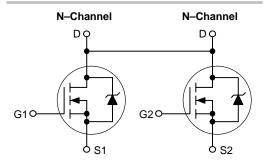
2. Surface Mounted to 1" x 1" FR4 Board.



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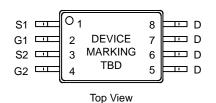
http://onsemi.com

5.8 AMPERES 20 VOLTS RDS(on) = 30 mΩ





MARKING DIAGRAM & PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping
NTQD6866	TSSOP-8	100 Units/Rail
NTQD6866R2	TSSOP-8	3000/Tape & Reel

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

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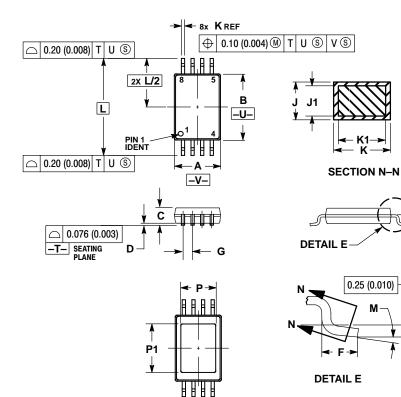
ELECTRICAL CHARACTERISTICS (T_C = 25° C unless otherwise noted)

Characteristic			Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage ($V_{GS} = 0 Vdc, I_D = 0.25 mAdc$) Temperature Coefficient (Positive)		V _(BR) DSS	20 _	_ TBD		Vdc mV/°C
Zero Gate Voltage Collector Current $(V_{DS} = 20 \text{ Vdc}, V_{GS} = 0 \text{ Vdc})$ $(V_{DS} = 20 \text{ Vdc}, V_{GS} = 0 \text{ Vdc}, T_J = 85^{\circ}\text{C})$		IDSS	-		1.0 25	μAdc
Gate–Body Leakage Current ($V_{GS} = \pm 12 \text{ Vdc}, V_{DS} = 0 \text{ Vdc}$)			-		100 100	nAdc
ON CHARACTERISTICS (Note 3.)						
Gate Threshold Voltage $(V_{DS} = V_{GS}, I_D = 0.25 \text{ mA})$ Temperature Coefficient (Negative)		V _{GS(th)}	0.6 _	0.9 TBD	1.2 -	Vdc mV/°C
Static Drain-to-Source On-State Resistance $(V_{GS} = 4.5 \text{ Vdc}, I_D = 7.0 \text{ Adc})$ $(V_{GS} = 4.0 \text{ Vdc}, I_D = 7.0 \text{ Adc})$ $(V_{GS} = 2.5 \text{ Vdc}, I_D = 3.5 \text{ Adc})$		R _{DS(on)}	- - -	TBD 0.026 0.031	TBD 0.030 0.040	Ω
Forward Transconductance (V_{DS} = 10 Vdc, I_{D} = 7.0 Adc)			TBD	17	-	Mhos
OYNAMIC CHARACTERISTICS						
Input Capacitance		C _{iss}	-	930	TBD	pF
Output Capacitance	− (V _{DS} = 10 Vdc, V _{GS} = 0 Vdc, f = 1.0 MHz)	C _{OSS}	_	370	TBD	
Transfer Capacitance		C _{rss}	_	105	TBD	
SWITCHING CHARACTERISTICS	Note 4.)					
Turn-On Delay Time		^t d(on)	_	8.6	TBD	ns
Rise Time	$(V_{DD} = 10 \text{ Vdc}, I_D = 1.0 \text{ Adc},$	t _r	_	14	TBD	-
Turn-Off Delay Time	- V _{GS} = 4.5 Vdc, R _L = 10, R _G = 6.0 Ω)	^t d(off)	_	57	TBD	
Fall Time		t _f	_	54	TBD	
Gate Charge	$(V_{DS} = 10 \text{ Vdc}, V_{GS} = 4.5 \text{ Vdc}, I_{D} = 5.8 \text{ Adc})$	QT	_	11	15	nC
		Q1	_	2.4	_	-
		Q2	_	2.4	_	
SOURCE-DRAIN DIODE CHARAC	TERISTICS				•	
Forward On–Voltage (Note 3.)	$(I_{S} = 1.8 \text{ Adc}, V_{GS} = 0 \text{ Vdc})$ $(I_{S} = 1.8 \text{ Adc}, V_{GS} = 0 \text{ Vdc}, T_{J} = 85^{\circ}\text{C})$	V _{SD}	-	0.7 TBD	1.0 -	Vdc
Reverse Recovery Time	(I _S = 1.5 Adc, V _{GS} = 0 Vdc, dI _S /dt = 100 A/μs)	t _{rr}	_	30	-	ns
		^t a	_	14.5	-	1
		t _b	_	15.5	-	1
Reverse Recovery Stored Charge		Q _{RR}	-	0.01	-	μC

Pulse Test: Pulse Width = 300 μs, Duty Cycle = 2%.
 Switching characteristics are independent of operating junction temperature.

PACKAGE DIMENSIONS

TSSOP-8 CASE 948S-01 PLASTIC **ISSUE O**



NOTES:

-W-

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. 4. DIMENSION P. DOES NOT INCLUDE INTERLEAD.
- (0.000) FER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- PER SIDE. 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	4.30	4.50	0.169	0.177
С		1.10		0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.70	0.020	0.028
G	0.65 BSC		0.026 BSC	
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
М	0 °	8°	0 °	8 °
Р		2.20		0.087
P1		3.20		0.126

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JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031 Phone: 81–3–5740–2745 Email: r14525@onsemi.com

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